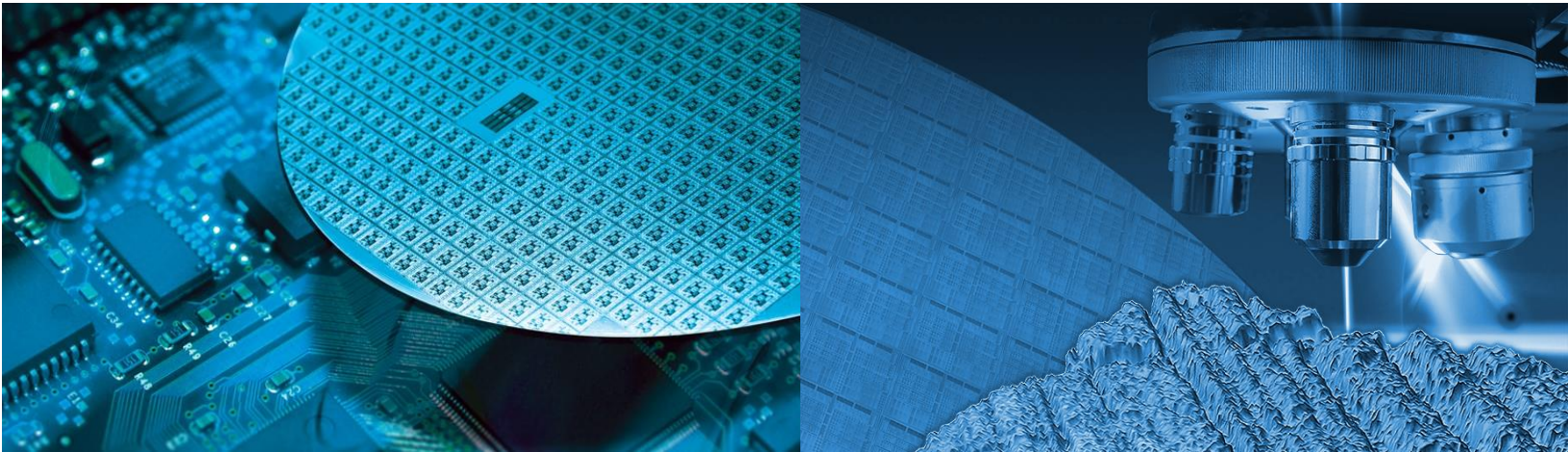


Join us for a Webinar

Optical Profiler Characterization of Electronic Devices & Packaging Using White Light Interferometry



2 June 2021, Wednesday, 10.00 AM



Register Here

Electronics devices are evolving rapidly with a variety of different processes and types. The goal to have more power and functionality with smaller form factor often associated with more complex design patterning making the process control and failure analysis critically vital.

Optical Metrology provide fast, accurate surface measurements to quantify a variety of key parameters including but not limited to roughness, flatness, coating thickness, trenches and imprint. These optical metrology systems are deployed throughout packaging processes from wire bonding to advanced chip level packaging, providing information critical for product functionality and quality control.

This webinar will give an introduction on the key working principle of white light interferometry and will focus mainly on the application examples and various case studies on its applications from front end die patterning to backend packaging process.

Joint Organizers



Moderator



Lim Sze Pei
Secretary
IEEE-EPS (Electronics Packaging Society), Malaysia Chapter
Indium Corporation

Speaker



Christopher Ong
Bruker Nano Surfaces